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WHAT IS CLAIMED IS:

1. An integrated circuit package comprising:

a printed circuit board;

a die attached to the printed circuit board; and

a heat spreader covering the die, the heat spreader contacting with backside of the die and being mounted to the printed circuit board.

2. The integrated circuit package as claimed in claim 1, wherein the heat spreader is formed by a piece body and a plurality of supporting leads extended downward from a periphery of the piece body.

Alo 3. The integrated circuit package as claimed in claim 2, wherein the piece body of the heat spreader abuts on the backside of the die, an interface with high thermal conductivity being filled between the piece body and the die.

A. The integrated circuit package as claimed in claim 3, wherein the interface with high thermal conductivity is thermal grease.

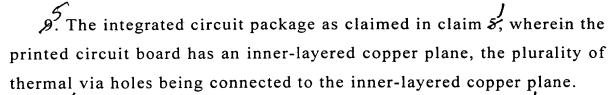
- 5. The integrated circuit package as claimed in claim 2, wherein the printed circuit board has a surface formed thereon a plurality of thermal pads disposed around the die.
- 6. The integrated circuit package as claimed in claim 5, wherein the plurality of supporting leads of the heat spreader are secured to the plurality of thermal pads on the printed circuit board, respectively.
- 7. The integrated circuit package as claimed in claim 6, wherein the plurality of supporting leads are secured to the plurality of thermal pads by surface mounting technology.

8. The integrated circuit package as claimed in claim 5, wherein the printed circuit board defines a plurality of thermal via holes at positions where the plurality of thermal pads are formed, respectively.

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10. The integrated circuit package as claimed in claim 5, wherein an additional heat sink is further mounted onto the piece body of the heat spreader.

The integrated circuit package as claimed in claim 5, wherein material with high thermal conductivity is filled between the plurality of supporting leads and the die.

The integrated circuit package as claimed in claim 1, wherein the material with high conductivity is thermal grease.